

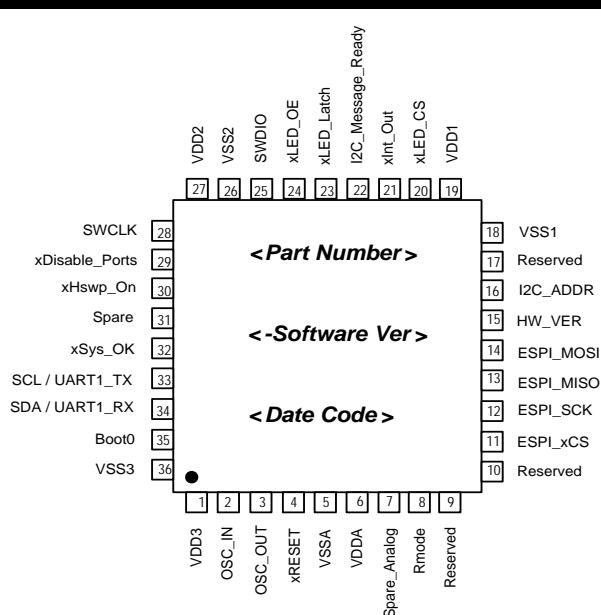
PoE Controller Unit
DATASHEET
DESCRIPTION

Microsemi's[™] PoE controller, PD69100, is a cost-effective, pre-programmed unit designed to implement Enhanced mode. It is used in conjunction with Microsemi's PoE Managers PD69108 and PD69104 in Ethernet switches to enable next generation network devices to share power and data over the same cable, as specified in IEEE802.3af and IEEE802.3at standards. Enhanced mode operation along with PD69108/PD69104 managers enables operation in a total Power-over-Ethernet stand-alone mode.

The controller features an ESPI bus for each PoE device and a communication interface with Host CPU via UART or I²C protocol.

Device is based on STMicroelectronics family STM32F101T6 embedded with ARM Cortex[™]-M3 core. It includes the following peripherals:

- 3 x Timers
- 2 x Uarts
- 1 x SPI
- 1 x I²C
- 1 x 12-bit analog-to-digital converter

PIN CONFIGURATION

KEY FEATURES

- ♦ Controls up to 48 PoE ports (6 x PD69108)
- ♦ Pre-Standard / Capacitor detection
- ♦ Detection of Cisco devices
- ♦ Supports both UART and I²C interfaces to Host CPU
- ♦ Backwards compatible with PD69000, PD63000, PD62000 and PDIC66000
- ♦ Supports 2 pair RJ or 4 pair RJ
- ♦ 16 power banks support using four discrete lines connected directly to PD69108 / PD69104.
- ♦ Power management for up to 96 ports
- ♦ Rmode pin for default parameters selection
- ♦ Programmable over-voltage and under voltage
- ♦ Predefined power budget; 16 discrete levels
- ♦ LED stream support
- ♦ System OK indication
- ♦ Software download via I²C or UART
- ♦ System and port measurements
- ♦ Detailed port status
- ♦ Thermal protection and monitoring
- ♦ Programmable temperature alarm limit
- ♦ Interrupt out pin for system and port events
- ♦ Forced power for system testing
- ♦ System reset
- ♦ Port power limit setting
- ♦ Port matrix and priority
- ♦ Automatic PoE device type detection
- ♦ RoHS compliant

MARKETING DEFINITIONS

Device's label includes the following:

- ♦ <Part number> Hardware P/N (for example PD69100)
- ♦ <-Software Ver> Software version (for example. 0120)
- ♦ <Date Code> Burning date code in the following format: yyww (yy = year, ww = week)

FIRMWARE DOWNLOAD

Initial burning of controller's firmware is performed in factory. Firmware upgrades can be performed by users using communication interface (see *application note 126 catalogue number 06-0006-080*).

ORDERING INFORMATION

Part Number	PD69100y-gggg
Detection	y = R: Resistor y = C: Resistor/legacy
Version	gggg

* For latest firmware version available, refer to Microsemi's website or Customer Care Support.



APPLICABLE DOCUMENTS

- ♦ IEEE 802.3af-2003 standard, DTE Power via MDI
- ♦ IEEE 802.3at-2009 standard, DTE Power via MDI
- ♦ Microsemi PD69108 datasheet , catalogue number DS_PD69108
- ♦ Microsemi PD69104 datasheet , catalogue number DS_PD69104
- ♦ Microsemi Serial communication protocol user guide , catalogue number 06-0054-080
- ♦ Microsemi application note 174 for Designing 48-port Enhanced PoE System (802.3af/802.3at Compliant), catalogue number 06-0054-080
- ♦ Microsemi Application note 126 Software Download for PoE Units, catalogue number 06-0006-080
- ♦ ST-Microelectronics STM32F101x6 datasheet

PIN FUNCTIONALITY

PIN	PIN NAME	PIN TYPE	PIN DESCRIPTION
1.	VDD3	Supply	Main Supply 3.3V
2.	OSC_IN	Oscillator	Oscillator Input
3.	OSC_OUT	Oscillator	Oscillator Output
4.	xRESET (NRST)	IN	Reset Input
5.	VSSA	AGND	Analog Ground
6.	VDDA	Supply	Main Supply 3.3V
7.	Spare_Analog	Analog_IN	N/A
8.	Rmode	Analog_IN	Pre Defined Power Budget Settings
9.	Reserved	OUT	Software Debug Uart
10.	Reserved	IN	Software Debug Uart
11.	ESPI_xCS	OUT	ESPI Bus to PoE Manager
12.	ESPI_SCK	OUT	ESPI Bus to PoE Manager
13.	ESPI_MISO	IN	ESPI Bus to PoE Manager
14.	ESPI_MOSI	OUT	ESPI Bus to PoE Manager
15.	HW_VER	Analog_IN	Hardware Version
16.	I2C_ADDR	Analog_IN	I2C address of PD69100
17.	Reserved	IN	Not Used (Must be Puledl Up)
18.	VSS1	DGND	Digital Ground
19.	VDD1	Supply	Main Supply 3.3V
20.	xLed_Cs	OUT	Chip Select for LED Stream

PIN	PIN NAME	PIN TYPE	PIN DESCRIPTION
21.	xlnt_Out	OUT	Interrupt Output Indication
22.	I2C_Message_Ready	OUT	Signals message is ready to be read by Host,
23.	xLED_Latch	OUT	Latch for LED stream
24.	xLED_OE	OUT	Enable for status LED
25.	SWDIO	DEBUG	Serial Debug Data Bus
26.	VSS2	DGND	Digital Ground
27.	VDD2	Supply	Main Supply 3.3V
28.	SWCLK	DEBUG	Serial Debug Data Bus Clock
29.	xDisable_Ports	IN	Disable all PoE Ports
30.	xHswp_On	OUT	External Hot Swap Device Enable
31.	Spare	SPARE I/O	N/A (PB4)
32.	xBsys_OK	OUT	System Validity Indication
33.	SCL / UART1_Tx	IN / OUT	I2C Clock or UART Transmit
34.	SDA / UART1_RX	IN / OUT	I2C Data or UART Receive
35.		input only Must pulled low	
	Boot0		Device Boot Configuration
36.	VSS3	DGND	Digital Ground

ELECTRICAL SPECIFICATION

For a detailed electrical specification refer to the following datasheets at www.st.com.

- **Manufacturer:** STMicroelectronics
- **Manufacturer part number:** STM32F101T6U6


MAIN FEATURES DESCRIPTION

Function	Description
Supports up to eight PoE devices – 96 ports	Up to 12 PoE devices can be cascaded, fitting into a 96 port PoE system that utilizes one PoE controller (PD69100)
Power Management	The system supports three power management modes: Class (LLDP) mode, Dynamic mode and Static mode. For more details see <i>technical note 113, catalogue number 06-0002-081</i> .
Threshold Configuration	Configure overvoltage and under-voltage thresholds for disconnection purposes.
High power ports, 2 pairs or 4 pairs	PoE devices can be configured (both hardware and software) to enable higher current through ports (up to ~720mA) or double power RJ in case of 4 pairs.
Communication	Supports both I ² C and UART interfaces with Host CPU.
Legacy (capacitor) Detection	Enables detection and powering of pre-standard devices (PDs).
LED Stream	Direct SPI interface to an external LED stream circuitry. Enables designers to implement a simple LED circuit that does not require a software code.
System OK Indication	Digital output pin to Host, indicating voltage and temperature range are valid.
System and Port Measurements	Measurements of the following parameters: Current (mA), Power Consumption (W), V _{main} (V), Port Voltage (V), PD Class (0-4).
Detailed Port Status	Port statuses are received from PoE managers. Statuses such as 'port on' and 'port off due to disconnection or due to overload'
Interrupt Pin	Interrupt out from PoE controller indicating events such as: port on, port off, port fault, PoE device fault, voltage out of range, and more. For a full list of interrupt events refer to <i>Serial Communication Protocol, catalogue number 06-0032-056</i> .
Port Power Limit	Configurable port power limit; when a port exceeds the limit, it is automatically disconnected
Port Matrix Control	Enables layout designers to connect all physical ports to logical ports whenever required.
'Power Good' Interrupt from Power Supply Directly to POE Drivers.	For systems comprising more than a single power supply, in case one power supply fails, a fast port disconnection mechanism is executed to maintain operation and prevent collapse of other power supplies.

I²C ADDRESS SELECTION

I²C interface between Host CPU and a specific PD69000 requires setting the device address; this is done by applying a specific voltage level to pin #25 (I2C_ADDR) as shown below:

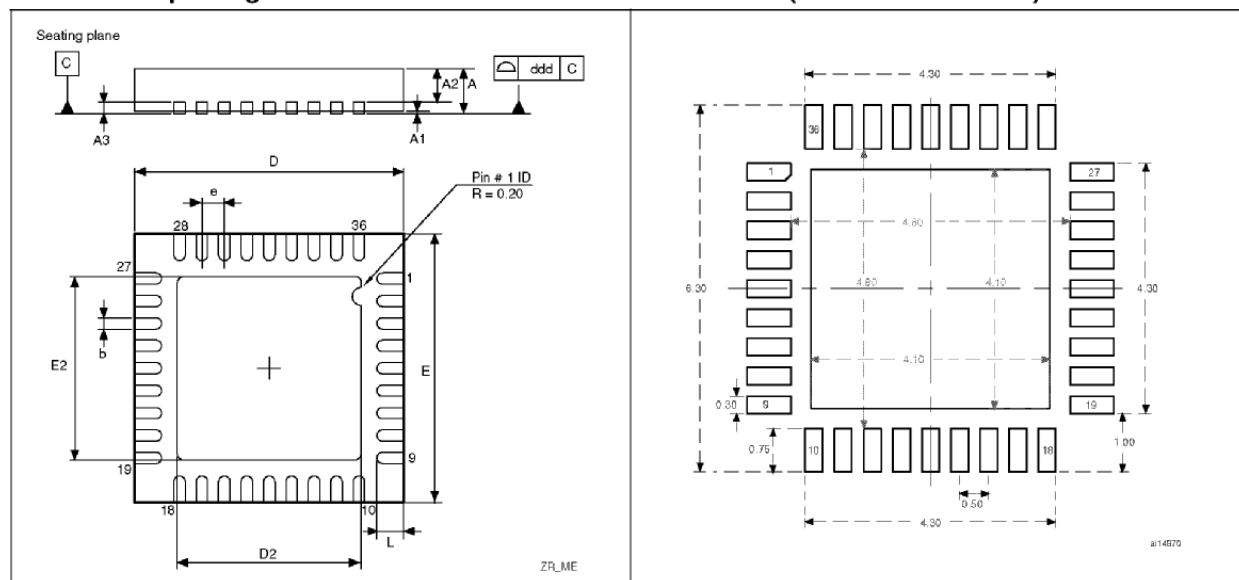
I2C_ADDR VOLTAGE LEVEL	I ² C ADDRESS (HEXADECIMAL)
0.00 to 0.21V _{DC}	UART
0.21 to 0.41V _{DC}	0x4
0.41 to 0.62V _{DC}	0x8
0.62 to 0.83V _{DC}	0xC
0.83 to 1.03V _{DC}	0x10
1.03 to 1.24V _{DC}	0x14
1.24 to 1.44V _{DC}	0x18
1.44 to 1.65V _{DC}	0x1C
1.65 to 1.86V _{DC}	0x20
1.86 to 2.06V _{DC}	0x24
2.06 to 2.27V _{DC}	0x28
2.27 to 2.48V _{DC}	0x2C
2.48 to 2.68V _{DC}	0x30
2.68 to 2.89V _{DC}	0x34
2.89 to 3.09V _{DC}	0x38
3.09 to 3.30V _{DC}	0x3C



PACKAGE INFORMATION

PD69100 is housed in a 36-pin VQFPN plastic package, 6 x 6 x 0.9 mm.

Figure 31. VFQFPN36 6 x 6 mm, 0.5 mm pitch, package outline⁽¹⁾ **Figure 32. Recommended footprint (dimensions in mm)⁽¹⁾⁽²⁾⁽³⁾**



1. Drawing is not to scale.
2. The back-side pad is not internally connected to the V_{SS} or V_{DD} power pads.
3. There is an exposed die pad on the underside of the VFQFPN package. It should be soldered to the PCB. All leads should also be soldered to the PCB.

Table 47. VFQFPN36 6 x 6 mm, 0.5 mm pitch, package mechanical data

Symbol	millimeters			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
A	0.800	0.900	1.000	0.0315	0.0354	0.0394
A1		0.020	0.050		0.0008	0.0020
A2		0.650	1.000		0.0256	0.0394
A3		0.250			0.0098	
b	0.180	0.230	0.300	0.0071	0.0091	0.0118
D	5.875	6.000	6.125	0.2313	0.2362	0.2411
D2	1.750	3.700	4.250	0.0689	0.1457	0.1673
E	5.875	6.000	6.125	0.2313	0.2362	0.2411
E2	1.750	3.700	4.250	0.0689	0.1457	0.1673
e	0.450	0.500	0.550	0.0177	0.0197	0.0217
L	0.350	0.550	0.750	0.0138	0.0217	0.0295
ddd		0.080			0.0031	

1. Values in inches are converted from mm and rounded to 4 decimal digits.

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Revision History

Revision Level / Date	Para. Affected	Description
0.1 / 15 February 2010		Initial release
0.2 Dec 2010		Ordering information update
1.1 / Jan 2011		Updating template and proofing

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